



N-channel Power MOSFET

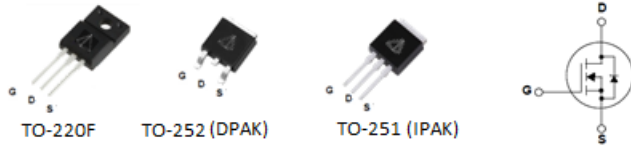
PRODUCT SUMMARY	
V _{DS} (V) at T _J max.	700
R _{DS(on)} max. at 25°C (mΩ)	V _{GS} =10V 360
Q _g max. (nC)	30
Q _{gs} (nC)	8.5
Q _{gd} (nC)	7.5
Configuration	single

Features

- New Technology For High Voltage Device
- ID=11.5A(Vgs=10V)
- Ultra Low Gate Charge
- Improved dv/dt Capability
- RoHS Compliant

Applications

- Switching Mode Power Supplies (SMPS)
- Power factor correction (PFC)
- Uninterruptible Power Supply (UPS)



ORDERING INFORMATION			
Device	SPC65R360G	SPE65R360G	SPD65R360G
Device Package	TO-220F	TO-251	TO-252
Marking	65R360G		

ABSOLUTE MAXIMUM RATINGS (T _C = 25°C, unless otherwise noted)				
Parameter	Symbol	Limit		Unit
		SPC65R360G	SPE65R360G SPD65R360G	
Drain to Source Voltage	V _{DSS}	650	650	V
Continuous Drain Current (@T _C =25°C)	I _D	11.5 ⁽¹⁾	11.5 ⁽¹⁾	A
Continuous Drain Current (@T _C =100°C)		7 ⁽¹⁾	7 ⁽¹⁾	A
Drain current pulsed ⁽²⁾		I _{DM}	42 ⁽¹⁾	42 ⁽¹⁾
Gate to Source Voltage	V _{GS}	±30	±30	V
Single pulsed Avalanche Energy ⁽³⁾	E _{AS}	144	144	mJ
MOSFET dv/dt ruggedness (@V _{DS} =0~400V)	dv/dt	25	25	V/ns
Peak diode Recovery dv/dt ⁽⁴⁾	dv/dt	15	15	V/ns
Total power dissipation (@T _C =25°C)	P _D	32.6	101	W
Derating Factor above 25°C		0.26	0.97	W/°C
Operating Junction Temperature & Storage Temperature	T _{STG} , T _J	-55 to + 150		°C
Maximum lead temperature for soldering purpose	T _L	260		°C
Mounting torque ⁽⁵⁾		0.4~0.6		N.m

Notes

1. Drain current is limited by maximum junction temperature.
2. Repetitive rating : pulse width limited by junction temperature.
3. L = 72mH, I_{AS} = 2A, V_{DD} = 50V, R_G=25Ω, Starting at T_J = 25°C
4. I_{SD} ≤ I_D, di/dt = 100A/us, V_{DD} ≤ BV_{DSS}, Starting at T_J = 25°C
5. Mounting consideration for TO220 Fullpack:
M3 screw plus flat washer is suggested, free of burr between devices and contact area,
the devices are to be mounted to a hole not larger than 3.6mm in contact diameter (chamfer included).



THERMAL CHARACTERISTICS				
Parameter	Symbol	Value		Unit
		SPC65R360G	SPE65R360G SPD65R360G	
Thermal resistance, Junction to case	R_{thjc}	3.83	1.24	°C/W
Thermal resistance, Junction to ambient	R_{thja}	80	62	°C/W

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise specified)						
Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain to source breakdown voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	650			V
Breakdown voltage temperature coefficient	$\Delta BV_{DSS} / \Delta T_J$	$I_D=250\mu A$, referenced to 25°C		0.7		V/°C
Drain to source leakage current	I_{DSS}	$V_{DS}=650V, V_{GS}=0V$			1	μA
		$V_{DS}=650V, T_C=125^\circ\text{C}$			10	μA
Gate to source leakage current, forward	I_{GSS}	$V_{GS}=30V, V_{DS}=0V$			100	nA
Gate to source leakage current, reverse		$V_{GS}=-30V, V_{DS}=0V$			-100	nA
On Characteristics						
Gate threshold voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2	3	4	V
Drain to source on state resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=6A$		300	360	m Ω
Forward Transconductance	G_{fs}	$V_{DS}=20V, I_D=6A$		8		S
Dynamic Characteristics						
Input capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=50V, f=1\text{MHz}$		1200		pF
Output capacitance	C_{oss}			45		
Reverse transfer capacitance	C_{rss}			3.5		
Turn on delay time	$t_{d(on)}$	$V_{DS}=380V, I_D=11.5A, R_G=18\Omega, V_{GS}=10V$		11		ns
Rising time	t_r			5		
Turn off delay time	$t_{d(off)}$			50		
Fall time	t_f			5		
Total gate charge	Q_g	$V_{DS}=480V, V_{GS}=10V, I_D=11.5A$		24	30	nC
Gate-source charge	Q_{gs}			8.5		
Gate-drain charge	Q_{gd}			7.5		

SOURCE TO DRAIN DIODE RATINGS CHARACTERISTICS						
Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous source current	I_S	Integral reverse p-n Junction diode in the MOSFET			11.5	A
Pulsed source current	I_{SM}				42	A
Diode forward voltage drop.	V_{SD}	$I_S=11.5A, V_{GS}=0V$		0.9	1.3	V
Reverse recovery time	T_{rr}	$I_S=11.5A, V_{GS}=0V, di/dt=100A/\mu s$		220		ns
Reverse recovery Charge	Q_{rr}				2.2	



Fig1. Output characteristics

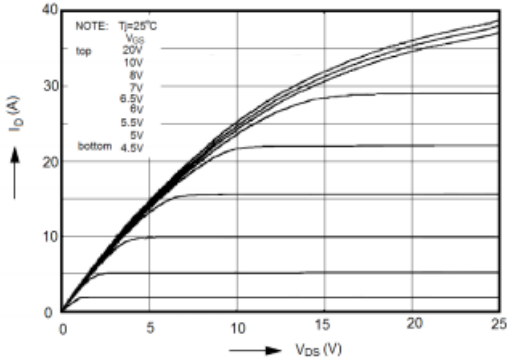


Fig2. Maximum Drain Current vs. Case Temperature

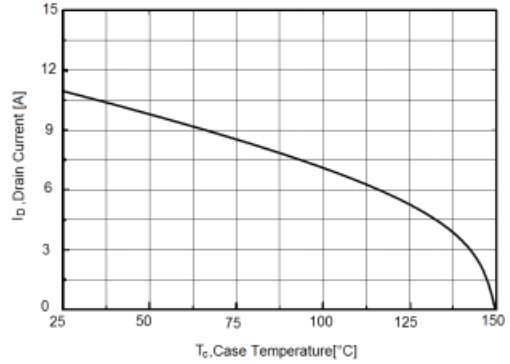


Fig3. Gate charge characteristics

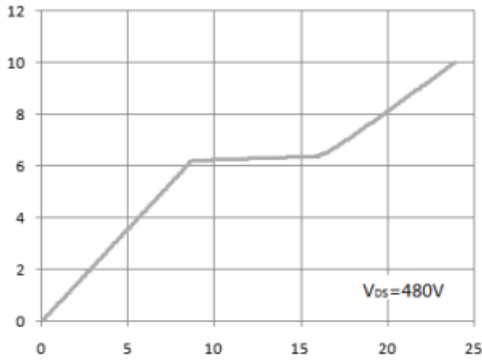


Fig 4. Capacitance Characteristics

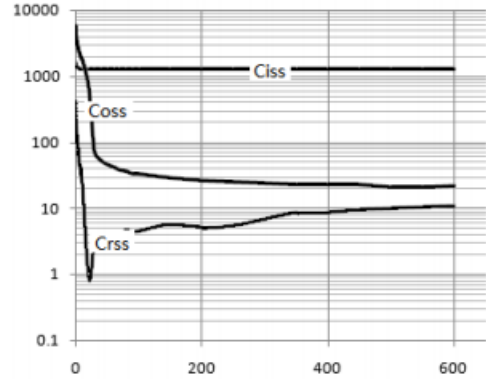


Fig 5. $R_{DS(ON)}$ vs junction temperature

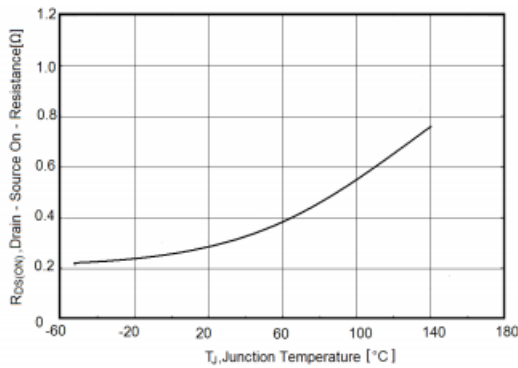


Fig 6. Temperature vs. Drain-to-Source Voltage

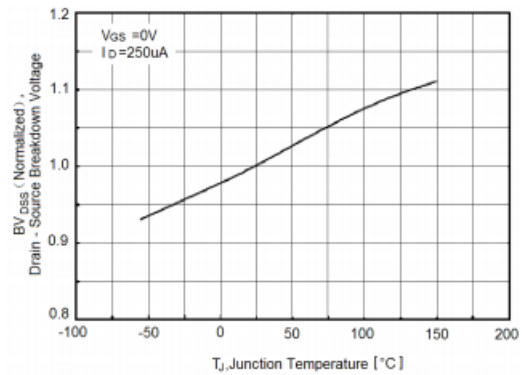




Fig 7 . Safe operating area (TO-220F)

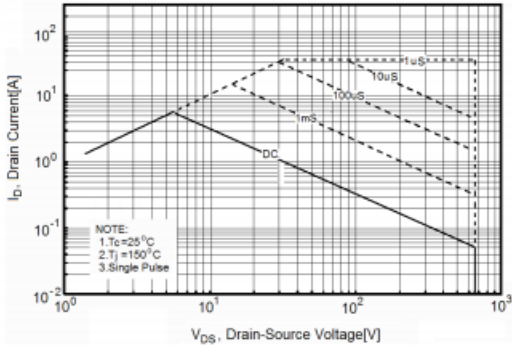


Fig 8 . Transient thermal impedance (TO-220F)

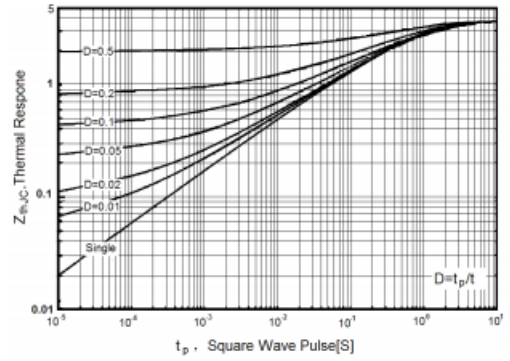


Fig 9 . Safe operating area (TO-251/252)

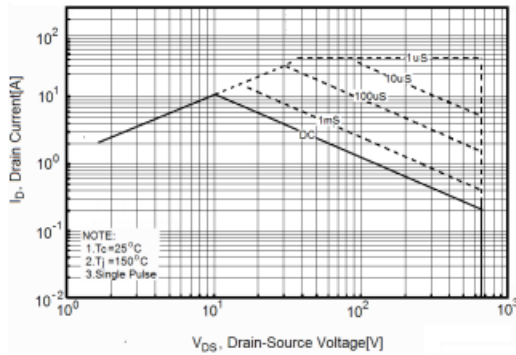


Fig 10 . Transient thermal impedance (TO-251/252)

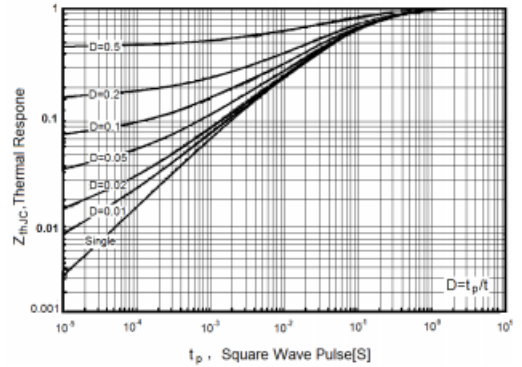


Fig 11. Forward characteristics of reverse diode

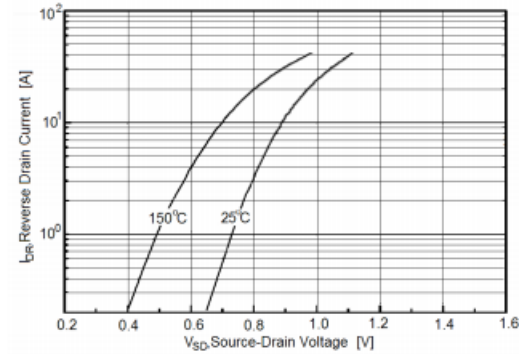


Fig 12 . Transfer characteristics

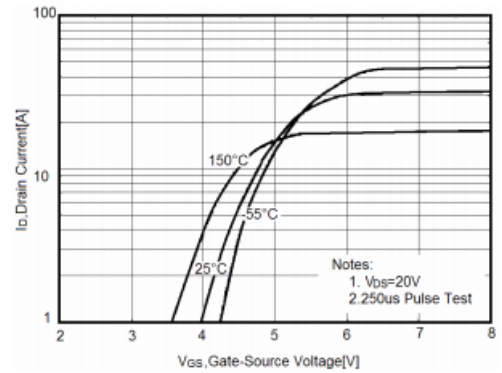


Fig 13. Gate charge test circuit & waveform

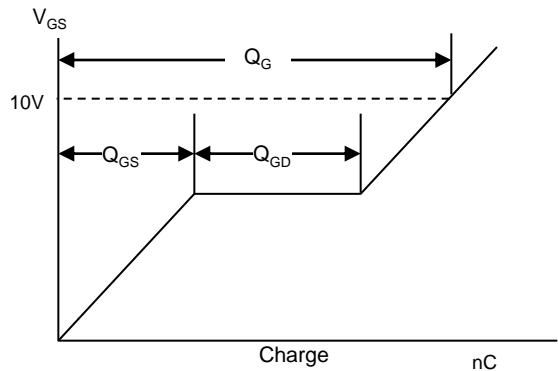
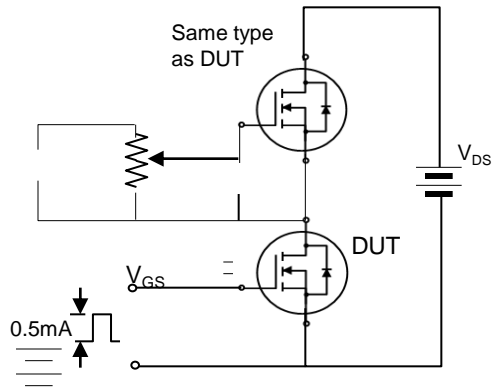


Fig 14. Switching time test circuit & waveform

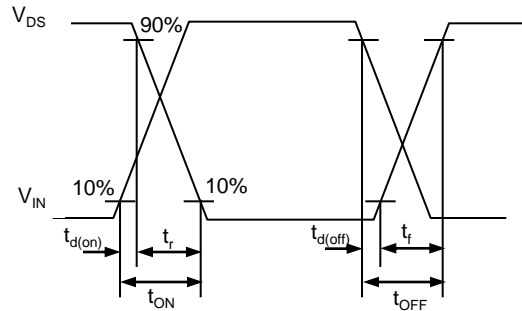
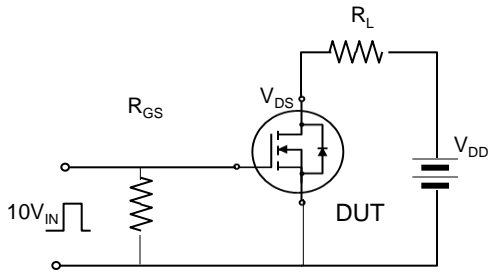


Fig 15. Unclamped Inductive switching test circuit & waveform

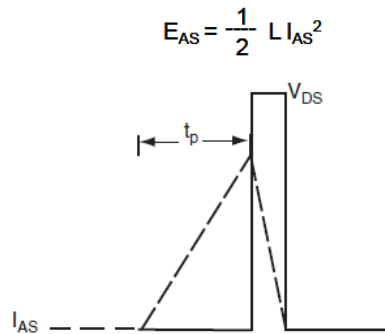
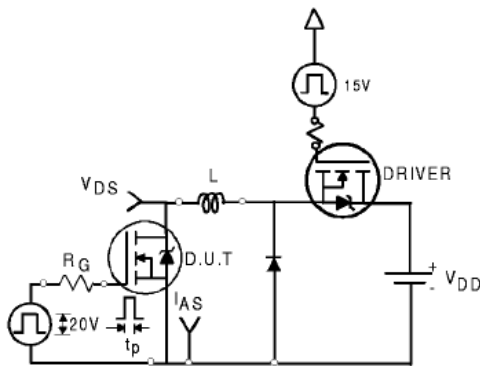
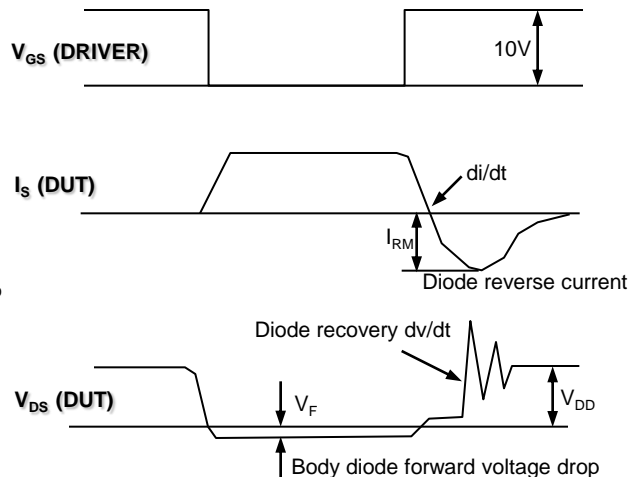
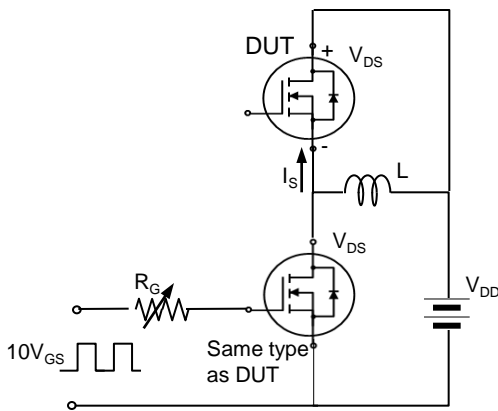


Fig 16. Peak diode recovery dv/dt test circuit & waveform



*. dv/dt controlled by R_G
 *. I_S controlled by pulse period



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